

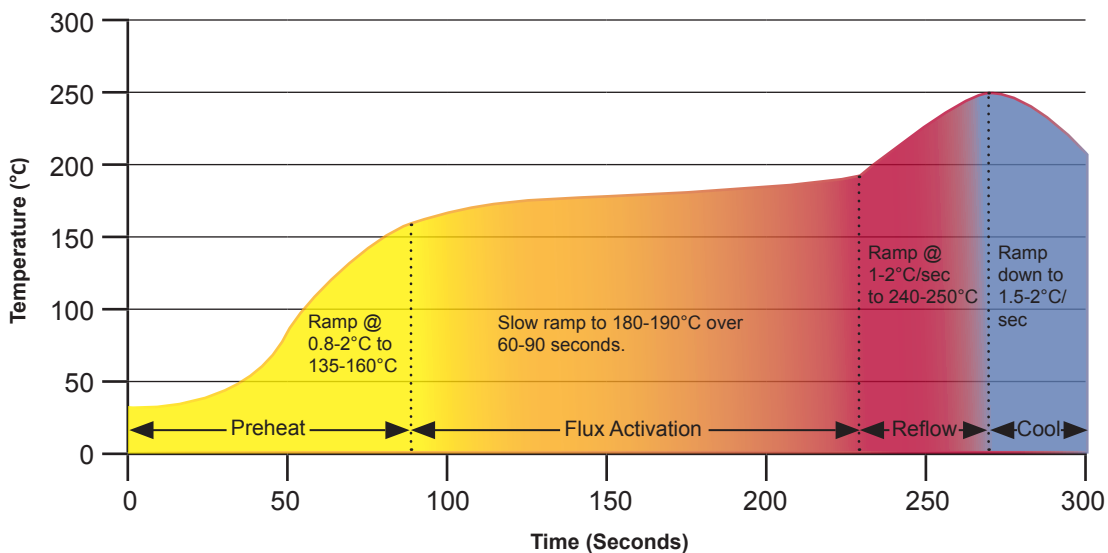
REFLOW PROFILE



Comus International's tilt switch packaging includes surface mount and through-hole technology. Several methods of soldering exist today, such as hand soldering, wave soldering and reflow soldering.

The most common method is reflow soldering. The reflow soldering process consists of applying solder paste on to a printed circuit board. This can be done by using a stencil plate or machinery. Next step is to populate the PCB with electrical components using a SMT machine. Once the board is populated, the final step is then conveying the PCB through an oven.

Below is an example of the recommended profile when using Alpha Omega 338 solder paste.



The physical properties of the solder paste: Alloys SAC305 (96.5%/Sn 3.0%Ag 0.5%Cu)

Reflow Guidelines:

Preheat - Ramp @ 0.8-2°C to 135°-160°C

Flux Activation - Slow ramp to 180°-190°C over 60-90 seconds.

Reflow - 1°-2°C/sec to 240°-250°C

Cool - Ramp down to 1.5°-2°C/sec

Should you have any questions or require additional information, please contact us at info@comus-intl.com